

N-Channel Logic Level Enhancement Mode Field Effect Transistor

BSS138W

Description

These N-Channel Enhancement Mode Field Effect Transistor. These products have been Designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance.

These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

Features

- $R_{DS(on)} = 3.5 \Omega$ @ $V_{GS} = 10 \text{ V}$, $I_D = 0.22 \text{ A}$ $R_{DS(on)} = 6.0 \Omega$ @ $V_{GS} = 4.5 \text{ V}$, $I_D = 0.22 \text{ A}$
- High Density Cell Design For Extremely Low R_{DS(on)}
- Rugged and Reliable
- Compact Industry Standard SOT-323 Surface Mount Package
- These Devices are Pb-Free and Halide Free

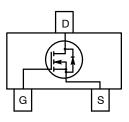
ABSOLUTE MAXIMUM RATINGS T_A = 25°C unless otherwise noted

Symbol	Parameter	Value	Unit
V _{DSS}	Drain to Source Voltage	50	V
V _{GSS}	Gate to Source Voltage	±20	V
I _D	Drain Current - Continuous (Note 1) - Pulsed	0.21 0.84	Α
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C
TL	Maximum Lead Temperature for Soldering Purposes, 1/16" from Case for 10 Seconds	300	°C

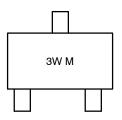
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



SOT-323, 3 Lead, 1.25X2 CASE 419AB



MARKING DIAGRAM



3W = Device Code
M = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
BSS138W	SOT-323 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, <u>BRD8011/D</u>.

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THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
P _D	Maximum Power Dissipation Derate Above 25°C (Note 1)	340 2.72	mW mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1)	367	°C/W

$\textbf{ELECTRICAL CHARACTERISTICS} \quad T_A = 25^{\circ}C \text{ unless otherwise noted}$

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Characteristics						
BV _{DSS}	Drain to Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	50	-	-	V
$\frac{\Delta BV_{DSS(th)}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	-	71	_	mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 50 V, V _{GS} = 0 V V _{DS} = 50 V, V _{GS} = 0 V, T _J = 125°C V _{DS} = 30 V, V _{GS} = 0 V	-	_	0.5 5 100	μΑ μΑ nA
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	-	±100	nA
On Charac	cteristics (Note2)					
V _{GS(th)}	Gate to Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 1mA$	0.8	1.3	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Threshold Voltage Temperature Coefficient	I _D = 1 mA, Referenced to 25°C	-	-3.9	-	mV/°C
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 0.22 A V _{GS} = 4.5 V, I _D = 0.22 A V _{GS} = 10 V, I _D = 0.22 A, T _J = 125°C	-	1.17 1.36 2.16	3.5 6.0 5.8	Ω Ω Ω
I _{D(on)}	On-State Drain Current	V _{GS} = 10 V, V _{DS} = 5 V	0.2		-	Α
9FS	Forward Transconductance	V _{DS} = 10 V, I _D = 0.22 A	0.12		-	S
Dynamic (Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1.0 \text{ MHz}$	-	38	-	pF
C _{oss}	Output Capacitance	1	-	5.9	-	pF
C _{rss}	Reverse Transfer Capacitance	1	-	3.5	-	pF
R_{g}	Gate Resistance	V _{GS} = 15 mV, f = 1.0 MHz	-	11	-	Ω
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 30 \text{ V}, I_D = 0.29 \text{ A},$	-	2.3	5	ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	-	1.9	18	ns
t _{d(off)}	Turn-Off Delay Time	1	-	6.7	36	ns
t _f	Turn-Off Fall Time	1	-	6.5	14	ns
Q_g	Total Gate Change	$V_{DS} = 25 \text{ V}, I_D = 0.22 \text{ A},$	_	1.1	_	nC
Q _{gs}	Gate-Source Change	V _{GS} = 10 V	_	0.12	-	nC
Q _{gd}	Gate-Drain Change	<u>]</u>	_	0.22	_	nC
Drain-Sou	rce Diode Characteristics					
IS	Maximum Continuous Drain-Source Diode Forward Current		-	_	0.22	Α
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 0 44 A (Note 2)	-	-	1.4	V
-						

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. 367°C/W When Mounted on a minimum pad.

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%

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TYPICAL CHARACTERISTICS

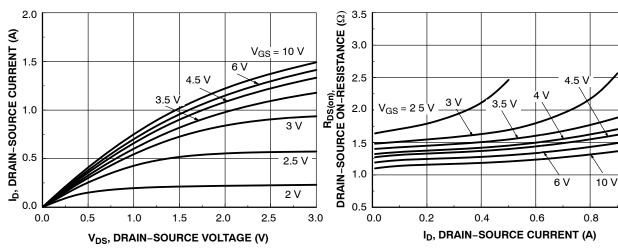
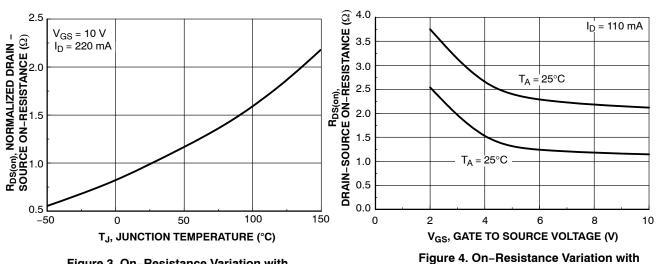


Figure 1. On-Region Characteristics

Figure 2. On-Resistance Variation With **Drain Current and Gate Voltage**

1.0



T_A = 125°C

T_A = 25°C

55(°C)

0.6

 $T_A =$

0.5

0.4

Figure 3. On-Resistance Variation with Temperature.

V_{DS}, DRAIN-SOURCE ON VOLTAGE (V) 0.0 0.0 0.0 0.0

0.0

0.1

0.2

 $V_{GS} = 10^{1} V$

1000 IS, REVERSE DRAIN CURRENT (mA) $V_{GS} = 0 V$ $T_A = 150^{\circ}C$ 100 $T_A = 25^{\circ}C$ 10 $T_A = -55^{\circ}C$

ID. DRAIN CURRENT (A) Figure 5. Drain-Source On Voltage with Temperature.

0.3

Figure 6. Body Diode Forward Voltage Variation with **Source Current and Temperature**

Gate-to-Source Voltage

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TYPICAL CHARACTERISTICS (continued)

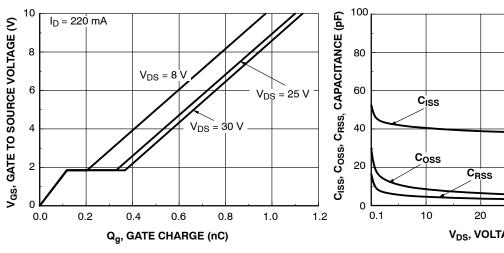
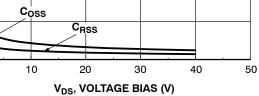


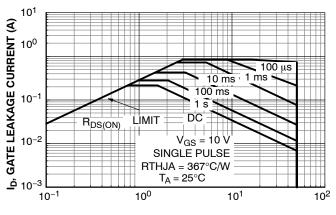
Figure 7. Gate Charge Characteristics



f = 1 MHz

V_{GS} = 0 V

Figure 8. Capacitance Characteristics



V_{DS}, DRAIN - SOURCE VOLTAGE (V)

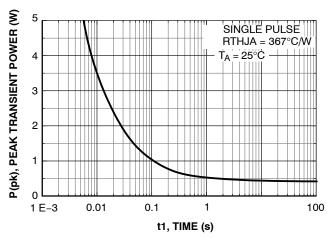


Figure 10. Single Pulse Maximum Power Dissipation

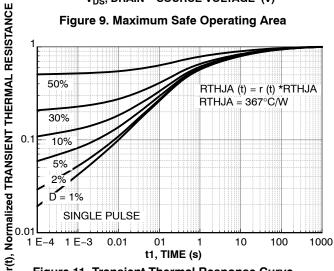
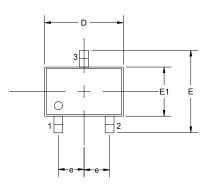


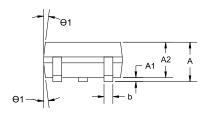
Figure 11. Transient Thermal Response Curve



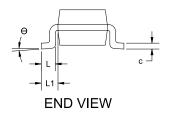




TOP VIEW



SIDE VIEW



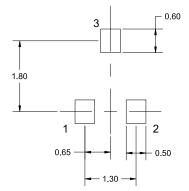
SC-70, 3 Lead, 1.25x2 CASE 419AB ISSUE A

DATE 13 FEB 2023

NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES IN DEGREES.
- 2. COMPLIES WITH JEDEC MO-203

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
Α	0.80		1.10
A1	0.00		0.10
A2	0.80	0.90	1.00
b	0.15		0.30
С	0.08		0.22
D	1.80	2.00	2.20
E	1.80	2.10	2.40
E1	1.15	1.25	1.35
е		0.65 BSC	
L	0.26	0.36	0.46
L1		0.42 REF	
θ	0°		8°
Θ1	4°		10°



SOLDERING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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